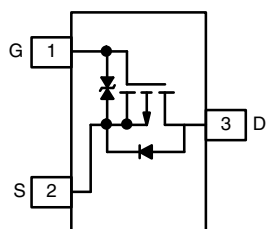


P-Channel 1.8 V (G-S) MOSFET

PRODUCT SUMMARY

V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (mA)
- 20	1.2 at $V_{GS} = - 4.5$ V	- 350
	1.6 at $V_{GS} = - 2.5$ V	- 300
	2.7 at $V_{GS} = - 1.8$ V	- 150

SC-75A or SC-89



Top View

SC-75A (SOT-416):
Si1013R - Marking Code D
SC-89 (SOT-490):
Si1013X - Marking Code B

Ordering Information:

Si1013R-T1-GE3 (SC-75A, Lead (Pb)-free and Halogen-free)
Si1013X-T1-GE3 (SC-89, Lead (Pb)-free and Halogen-free)

FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- High-Side Switching
- Low On-Resistance: 1.2 Ω
- Low Threshold: 0.8 V (Typ.)
- Fast Switching Speed: 14 ns
- 1.8 V Operation
- TrenchFET® Power MOSFETs
- 2000 V ESD Protection
- Compliant to RoHS Directive 2002/95/EC



RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories
- Battery Operated Systems
- Power Supply Converter Circuits
- Load/Power Switching Cell Phones, Pagers

BENEFITS

- Ease in Driving Switches
- Low Offset (Error) Voltage
- Low-Voltage Operation
- High-Speed Circuits
- Low Battery Voltage Operation

ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C, unless otherwise noted)

Parameter		Symbol	5 s	Steady State	Unit
Drain-Source Voltage		V_{DS}	- 20		V
Gate-Source Voltage		V_{GS}	± 6		
Continuous Drain Current ($T_J = 150\text{ }^{\circ}\text{C}$) ^b	$T_A = 25\text{ }^{\circ}\text{C}$	I_D	- 400	- 350	mA
	$T_A = 85\text{ }^{\circ}\text{C}$		- 300	- 275	
Pulsed Drain Current ^a		I_{DM}	- 1000		
Continuous Source Current (Diode Conduction) ^b		I_S	- 275	- 250	
Maximum Power Dissipation ^b for SC-75	$T_A = 25\text{ }^{\circ}\text{C}$	P_D	175	150	mW
	$T_A = 85\text{ }^{\circ}\text{C}$		90	80	
Maximum Power Dissipation ^b for SC-89	$T_A = 25\text{ }^{\circ}\text{C}$		275	250	
	$T_A = 85\text{ }^{\circ}\text{C}$		160	140	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to 150		$^{\circ}\text{C}$
Gate-Source ESD Rating (HBM, Method 3015)		ESD	2000		V

Notes:

- a. Pulse width limited by maximum junction temperature.
b. Surface mounted on FR4 board.

SPECIFICATIONS ($T_A = 25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = -250\ \mu\text{A}$	-0.45			V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\ \text{V}$, $V_{GS} = \pm 4.5\ \text{V}$		± 1	± 2	μA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -16\ \text{V}$, $V_{GS} = 0\ \text{V}$		-0.3	-100	nA
		$V_{DS} = -16\ \text{V}$, $V_{GS} = 0\ \text{V}$, $T_J = 85^\circ\text{C}$			-5	μA
On-State Drain Current ^a	$I_{D(on)}$	$V_{DS} = -5\ \text{V}$, $V_{GS} = -4.5\ \text{V}$	-700			mA
Drain-Source On-State Resistance ^a	$R_{DS(on)}$	$V_{GS} = -4.5\ \text{V}$, $I_D = -350\ \text{mA}$		0.8	1.2	Ω
		$V_{GS} = -2.5\ \text{V}$, $I_D = -300\ \text{mA}$		1.2	1.6	
		$V_{GS} = -1.8\ \text{V}$, $I_D = -150\ \text{mA}$		1.8	2.7	
Forward Transconductance ^a	g_{fs}	$V_{DS} = -10\ \text{V}$, $I_D = -250\ \text{mA}$		0.4		S
Diode Forward Voltage ^a	V_{SD}	$I_S = -150\ \text{mA}$, $V_{GS} = 0\ \text{V}$		-0.8	-1.2	V
Dynamic^b						
Total Gate Charge	Q_g	$V_{DS} = -10\ \text{V}$, $V_{GS} = -4.5\ \text{V}$, $I_D = -250\ \text{mA}$		1500		pC
Gate-Source Charge	Q_{gs}			150		
Gate-Drain Charge	Q_{gd}			450		
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = -10\ \text{V}$, $R_L = 47\ \Omega$ $I_D \cong -200\ \text{mA}$, $V_{GEN} = -4.5\ \text{V}$, $R_g = 10\ \Omega$		5		ns
Rise Time	t_r			9		
Turn-Off Delay Time	$t_{d(off)}$			35		
Fall Time	t_f			11		

Notes:

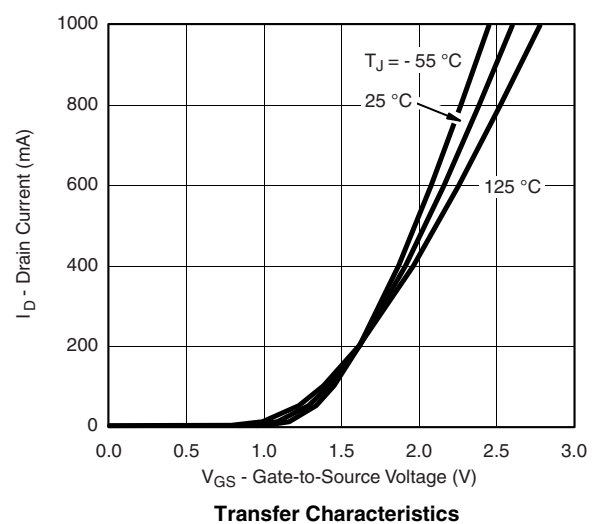
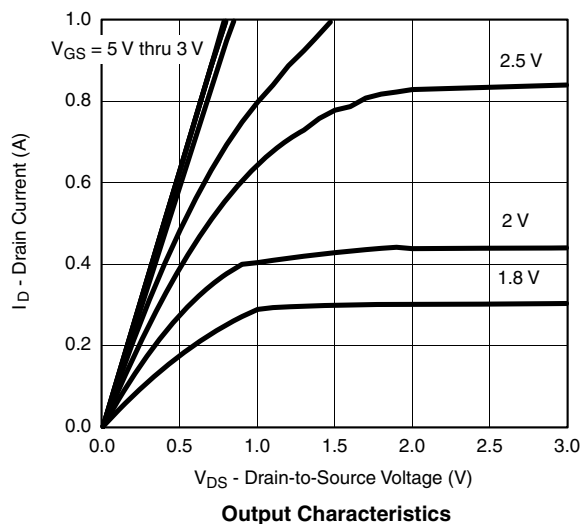
a. Pulse test; pulse width $\leq 300\ \mu\text{s}$, duty cycle $\leq 2\%$.

b. Guaranteed by design, not subject to production testing.

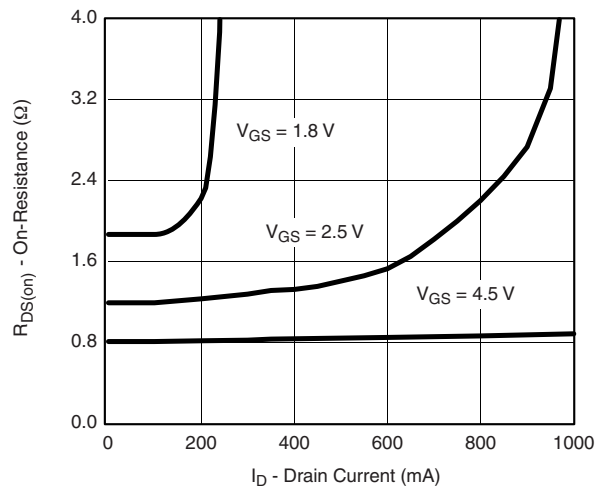
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise noted)

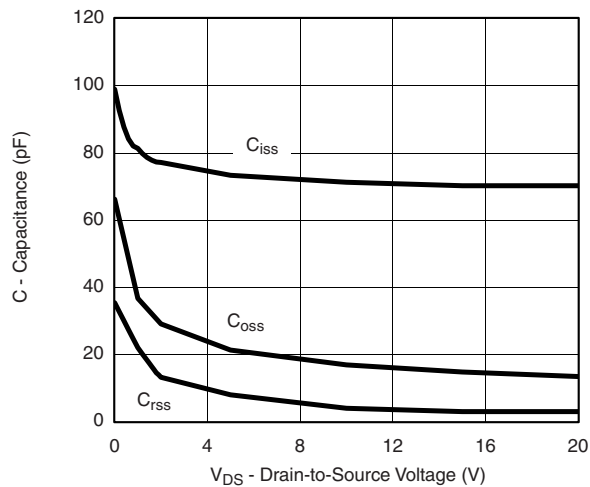
For the following graphs, P-Channel negative polarities for all voltage and current values are represented as positive values.



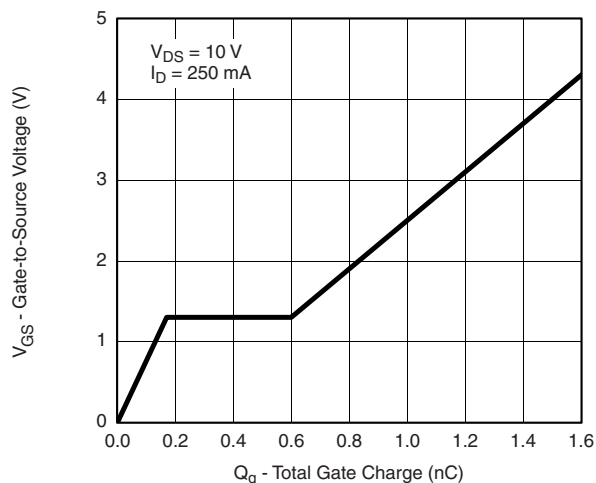
TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise noted)



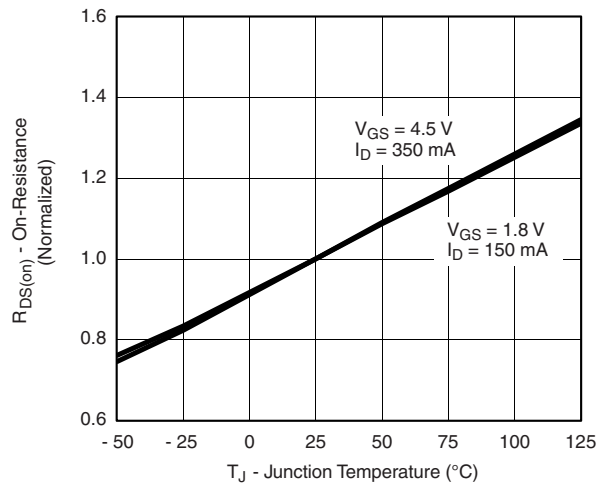
On-Resistance vs. Drain Current



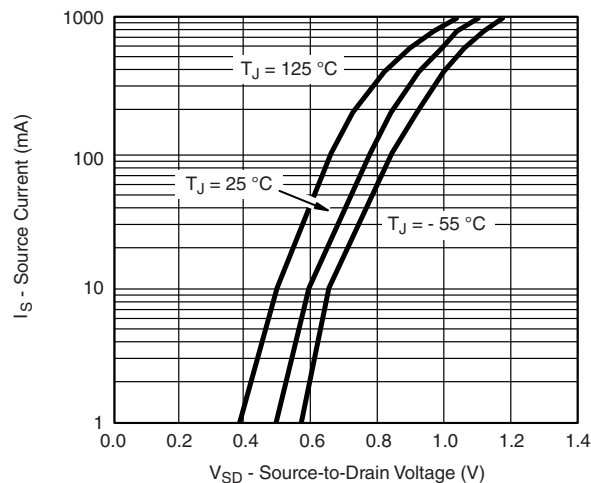
Capacitance



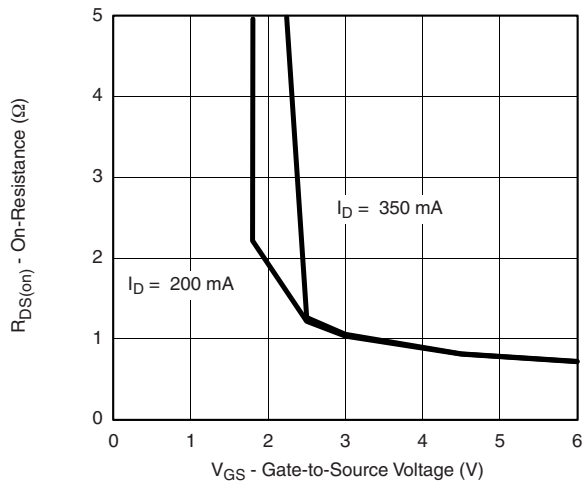
Gate Charge



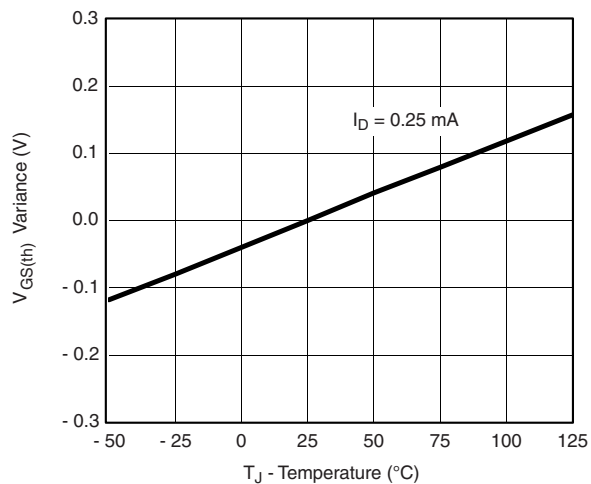
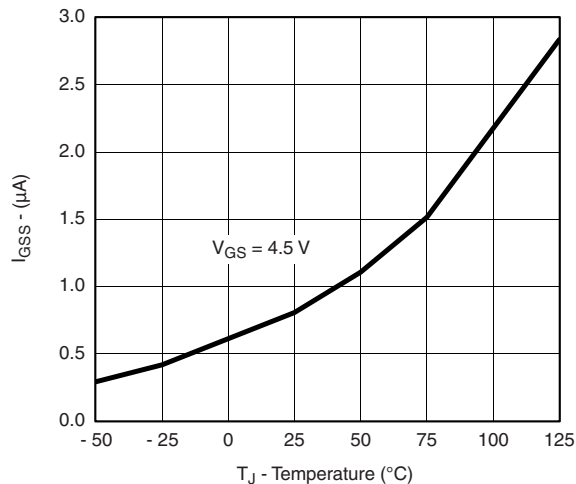
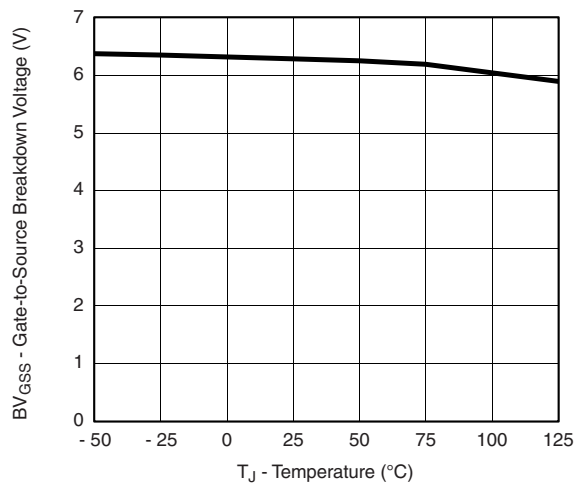
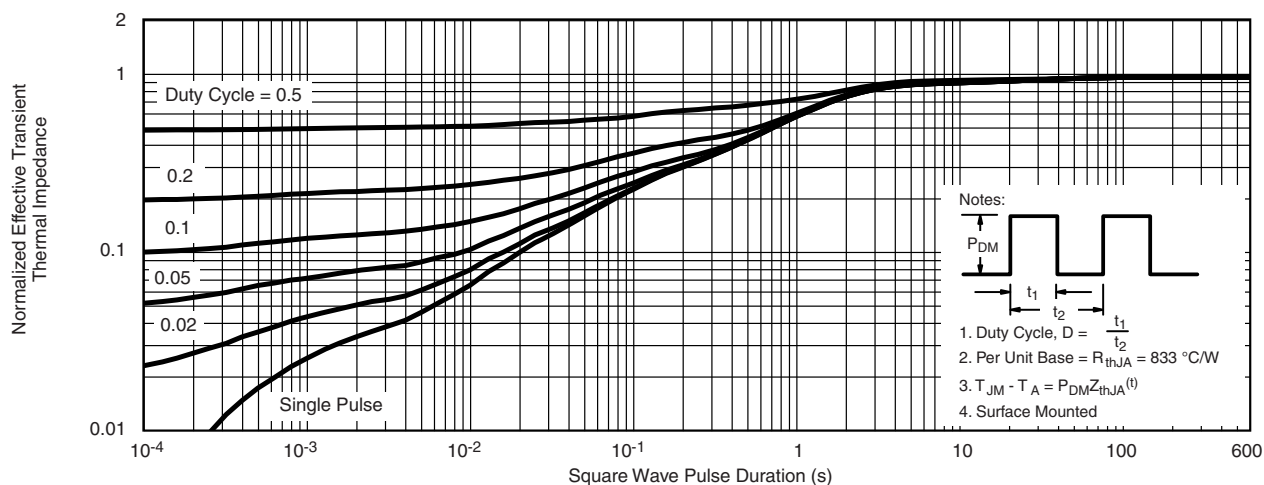
On-Resistance vs. Junction Temperature



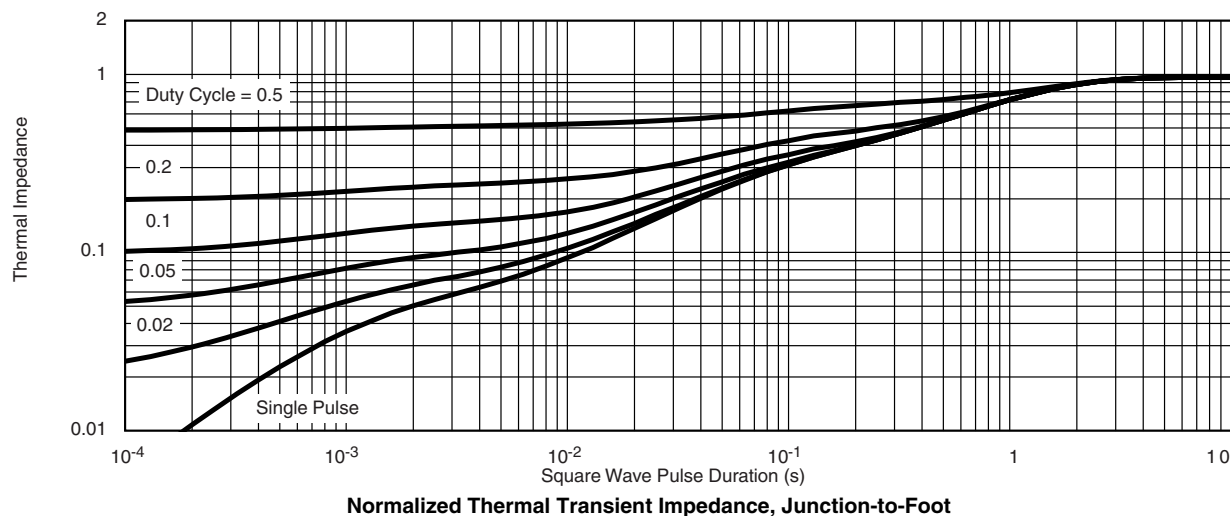
Surge-Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage

TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise noted)**Threshold Voltage Variance vs. Temperature** **I_{GSS} vs. Temperature** **BV_{GSS} vs. Temperature****Normalized Thermal Transient Impedance, Junction-to-Ambient (SC-75A)**

TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)



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